

## CONTROLLED AVALANCHE RECTIFIER DIODES

Glass passivated rectifier diodes in hermetically sealed axial-leaded ID\* envelopes and intended for general purpose rectifier applications.

The device is capable of absorbing reverse transient energy.

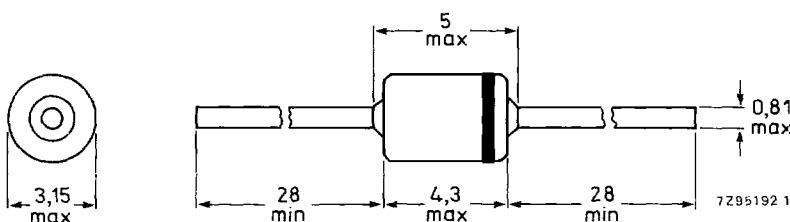
## QUICK REFERENCE DATA

		BYD14D	G	J	K	M	
Crest working voltage	V <sub>RWM</sub>	max.	200	400	600	800	1000 V
Reverse avalanche breakdown voltage	V <sub>(BR)R</sub>	> <	225 1600	450 1600	650 1600	900 1600	1100 V
Average forward current	I <sub>F(AV)</sub>	max.		2			A
Non-repetitive peak forward current	I <sub>FSM</sub>	max.		50			A
Non-repetitive peak reverse avalanche energy	E <sub>RSM</sub>	max.		40			mJ
Junction temperature	T <sub>j</sub>	max.		175			°C

## MECHANICAL DATA

Dimensions in mm

Fig. 1 SOD-84.



The marking band indicates the cathode.

\* Implosion Diode.

**RATINGS**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

		BYD14D	G	J	K	M	V
Crest working voltage	$V_{RWM}$	max.	200	400	600	800	1000 V
Continuous reverse voltage	$V_R$	max.	200	400	600	800	1000 V
Average forward current (averaged over any 20 ms period)							
$T_{tp} = 45^\circ\text{C}$ ; lead length 10 mm	$I_{F(AV)}$	max.			2		A
$T_{amb} = 60^\circ\text{C}$ ; see Fig. 2	$I_{F(AV)}$	max.			1		A
Repetitive peak forward current							
$T_{tp} = 45^\circ\text{C}$ ; $f = 50 \text{ Hz}$ ; $a = 4,5$ (inclusive derating for $T_{jmax}$ at $V_{RRM} = 1000 \text{ V}$ )	$I_{FRM}$	max.			20		A
Non-repetitive peak forward current $t = 10 \text{ ms}$ , half-sinewave (see Fig. 10)	$I_{FSM}$	max.			50		A
Non-repetitive peak reverse avalanche energy; $I_R = 0,8 \text{ A}$ ; $T_j = 25^\circ\text{C}$ prior to surge; with inductive load switched off	$E_{RSR}$	max.			40		mJ
Storage temperature	$T_{stg}$				-65 to +175		°C
Junction temperature	$T_j$	max.			175		°C

**THERMAL RESISTANCE**

Influence of mounting method

1. Thermal resistance from junction to tie-point at a lead length of 10 mm       $R_{th\ j\ -tp} =$       50      K/W
2. Thermal resistance from junction to ambient; device mounted on an 1,5 mm thick epoxy-glass printed circuit board; Cu-thickness  $\geq 40 \mu\text{m}$ ;  
Fig. 2 (see "Thermal model")       $R_{th\ j\ -a} =$       105      K/W

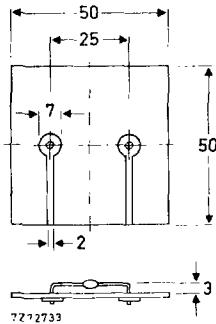
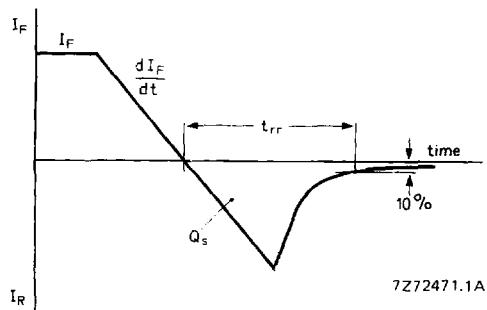


Fig. 2 Mounted on a printed-circuit board.

## CHARACTERISTICS

 $T_j = 25^\circ\text{C}$  unless otherwise specified

		BYD14D	G	J	K	M
Forward voltage*						
$I_F = 3 \text{ A}$	$V_F$	<	1,15	1,15	1,15	1,15
$I_F = 3 \text{ A}; T_j = T_{j\max}$	$V_F$	<	1,05	1,05	1,05	1,05
Reverse avalanche breakdown voltage						
$I_R = 0,1 \text{ mA}$	$V_{(BR)R}$	>	225	450	650	900
		$\leq$	1600	1600	1600	1600
Reverse current						
$V_R = V_{RWMmax}^{**}$	$I_R$	<		1		$\mu\text{A}$
$V_R = V_{RWMmax}; T_j = 165^\circ\text{C}$	$I_R$	<		150		$\mu\text{A}$
Reverse recovery when switched from						
$I_F = 1 \text{ A}$ to $V_R \geq 30 \text{ V}$ with						
$-dI_F/dt = 5 \text{ A}/\mu\text{s}$						
recovery charge	$Q_s$	typ.		3		$\mu\text{C}$
recovery time	$t_{rr}$	typ.		2,5		$\mu\text{s}$
Diode capacitance at $f = 1 \text{ MHz}$						
$V_R = 0$	$C_d$	typ.		50		$\text{pF}$

Fig. 3 Definitions of  $t_{rr}$ ,  $Q_s$  and  $dI_F/dt$ .

\* Measured under pulse conditions to avoid excessive dissipation.

\*\* Illuminance  $\leq 500 \text{ lux}$  (daylight); relative humidity  $< 65\%$ .

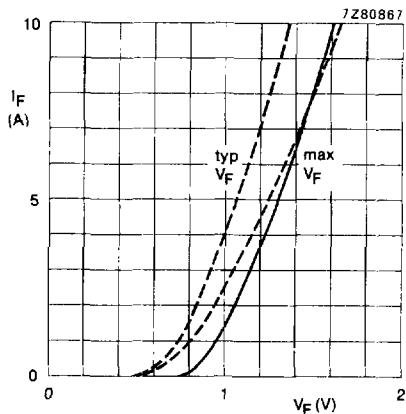


Fig. 4 Forward voltage;  
 ———  $T_j = 25^\circ\text{C}$ ; .....  $T_j = 175^\circ\text{C}$ .

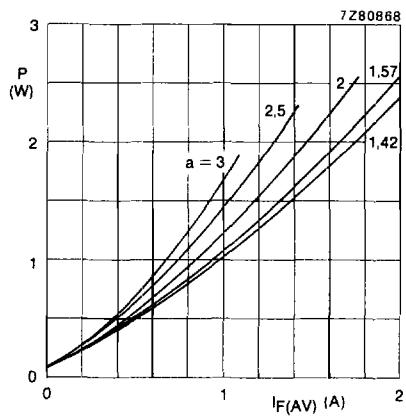


Fig. 5 Maximum values steady state power dissipation (forward plus leakage current) as a function of the average a forward current.  
 $a = I_F(\text{RMS})/I_F(\text{AV})$ ;  $V_R = V_{\text{RWMmax}}$ .

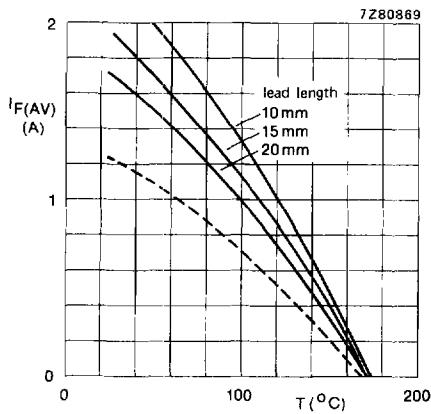


Fig. 6 Maximum average forward current as a function of temperature; the curves include losses due to reverse leakage.  
 $V_R = V_{\text{RWMmax}}$ ,  $\delta = 0.5$ ;  $a = 1.57$ .  
 ----- = ambient temperature and device mounted as shown in Fig. 2  
 ——— = tie-point temperature

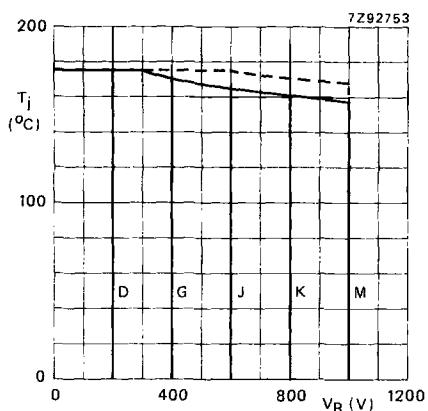


Fig. 7 Maximum permissible junction temperature as a function of reverse voltage;  
 $\text{---} = V_R$ ;  $\text{-----} = V_{RWM}$ ,  $\delta = 0.5$ ,  
device mounted as shown in Fig. 2.

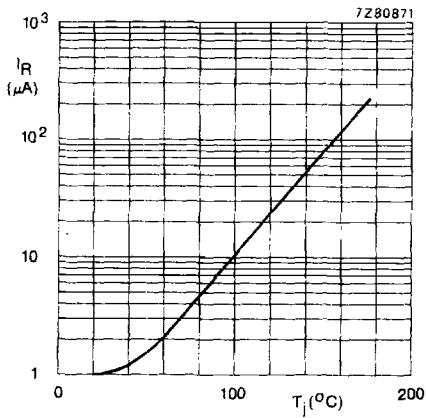


Fig. 8 Maximum values reverse current as a function of junction temperature;  
 $V_R = V_{RWMmax}$ .

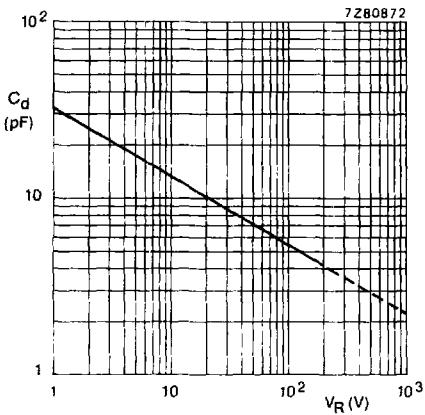


Fig. 9 Capacitance as a function of reverse voltage;  $f = 1 \text{ MHz}$ ;  $T_j = 25 \text{ }^{\circ}\text{C}$ ; typical values.

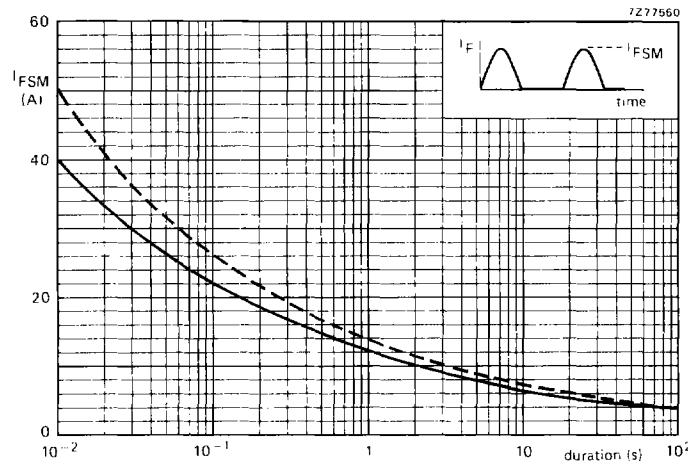


Fig. 10 Maximum permissible non-repetitive peak forward current based on sinusoidal currents;  $f = 50$  Hz.

-----  $T_j = 25^\circ\text{C}$  prior to surge;  $V_R = 0$   
 —————  $T_j = T_j \text{ max}$  prior to surge;  $V_R = V_{RWM} \text{ max}$ .

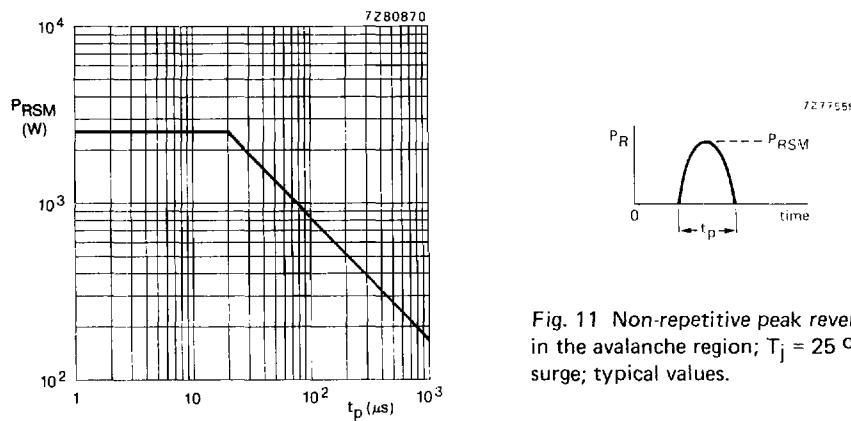


Fig. 11 Non-repetitive peak reverse power in the avalanche region;  $T_j = 25^\circ\text{C}$  prior to surge; typical values.